1

	产品规格承认书	
	SPECIFICATIONS	
客户:		
CUSTOMER:		

产品名称:	
DESCRIPTION:	Chip Antenna
客户型号:	
CUSTOMER PART	NO:
产品型号:	
OUR MODEL NO:	PBX1608MC01
日期:	
DATE:	

确认签字,盖章后请返回承认书一份

PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL"

WITH YOUR APPROVED SIGNATURES

客户承認	
 CUSTOMER APPROVED	

	工 程 部 R&D CENTER	
承 認 APPROVAL	確認 CHECKED	製 作 DRAWN
Ray	Tennyson	Snow

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SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF F		-
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TITLE, CHIP2450-1608 Sr	pecification			SPEC REV.
TITLE: CHIP2450-1608 Specification		NO.	1008	P1

PBX1608MC01 Specification

1. Features:

- Stable and reliable in performances
- Low profile, compact size
- RoHS compliance
- SMT processes compatible

2. APPLICATIONS:

- ISM 2 . 4 GHz applications
- ZigBee/BLE applications
- Bluetooth earphone systems
- Hand-held devices when WiFi/Bluetooth functions are needed, e.g., Smart phones
- IEEE802.11 b/g/n
- Wireless PCMCIA cards or USB dongles

3. Part Number Information

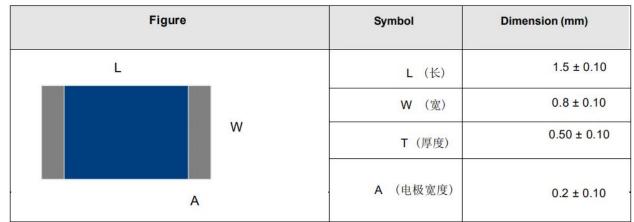
AN	1608	S	<u>24</u>	LS
Α	В	С	D	E

Α	Product Series	Antenna
B	Dimension L x W	1.6X0.8mm (+-0.2mm)
С	Antenna type	S:Chip antenna
D	Working Frequency	2.4 ~ 2.5GHz
Ε	Product type	LS

UNLESS OTHER SPECIAL X=± X.X=± ANGLES = ±	FIED TOLERANCES ON: X.XX= HOLEDIA=±	: Shenzhen Pengbian Industrial Technology Co., LTD Room 605, Building 4, 1970 Science Park, Minzhi Community, Minzhi Street, Longhua District, Shenzhen		nunity,
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	pecification	NO.	1000	P1

4. Product dimensions:

1608 Chip Antenna

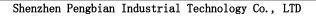


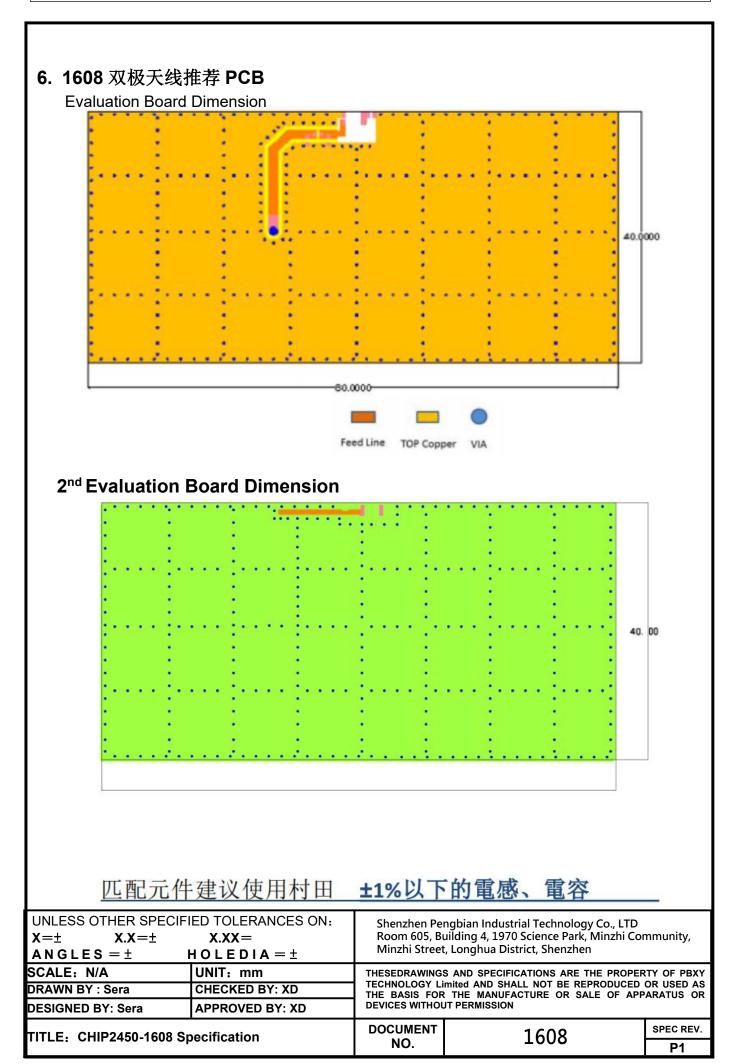
5. Electrical Specification:

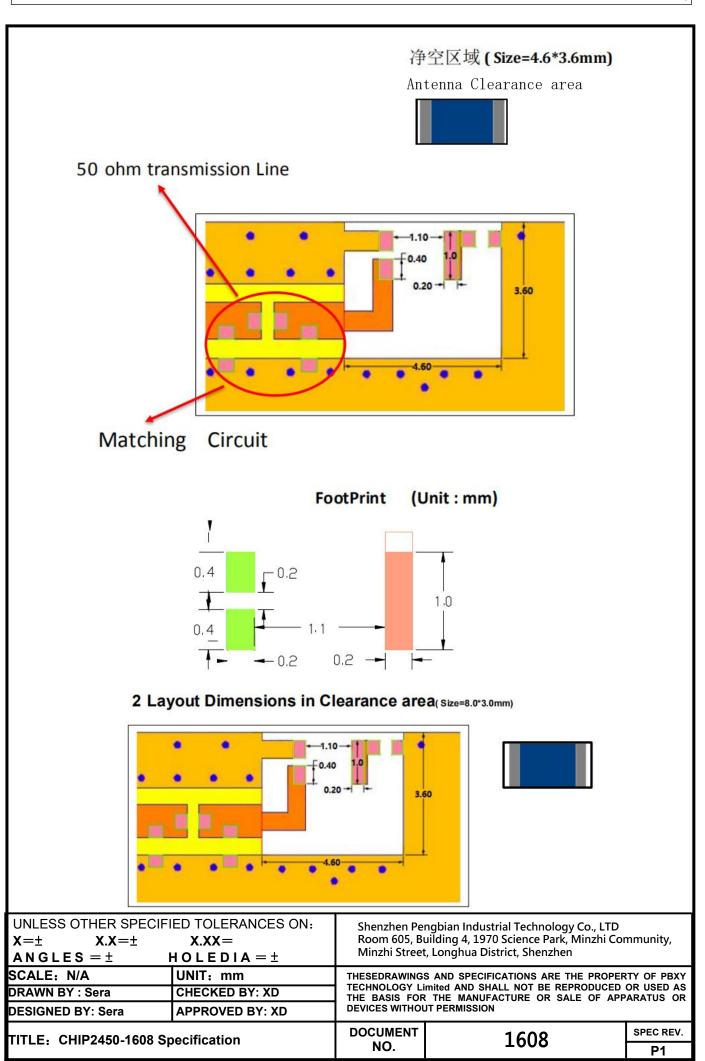
Specification				
Part Number	AN1608S24LS			
Central Frequency	2450	MHz		
Bandwidth	120 (Min.)	MHz		
Return Loss	-6.5 (Max)	dB		
Peak Gain	1.66	dBi		
Impedance	50	Ohm		
Operating Temperature	-40 [~] +85	C		
Maximum Power	4	W		
Resistance to Soldering Heats	10 (@ 260C)	sec.		
Polarization	Linear			
Azimuth Beamwidth	Omni-directiona	al		
Termination	Ni / Sn (Leadless	s)		

Remark : Bandwidth & Peak Gain was measured under evaluation board of next page

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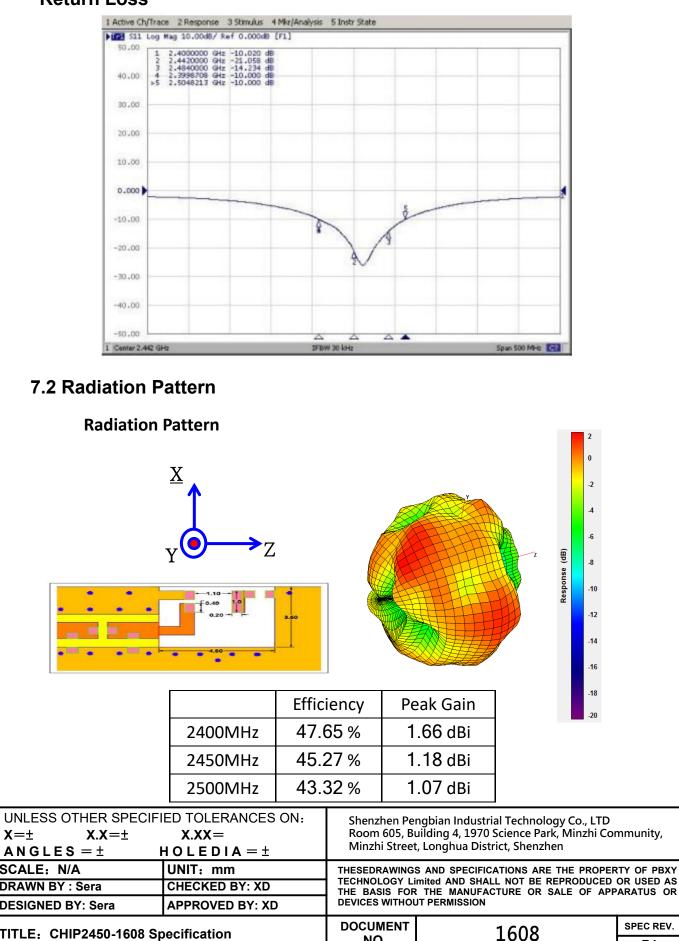








Return Loss



NO.

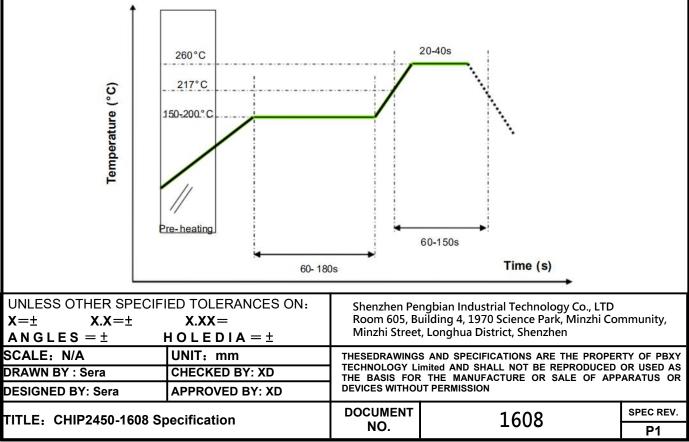
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P1

8. Raliability and Test Condictions

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6 JESD22-B102D	*Solder bath temperature : 235 ± 5°C *Immersion time : 2 ± 0.5 sec Solder : Sn3Ag0.5Cu for lead-free	At least 95% of a surface of each terminal electrode must be covered by fresh solder.
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}C$ *Leaching immersion time : 30 ± 0.5 sec Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5± 1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics unde the operational temperature range within -40 ~85°C.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : 120~150C , 1 minute. *Solder temperature : 270±5°C *Immersion time : 10± 1 sec Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics unde the operational temperature range within -40 ~ 85°C. Loss of metallization on the edges of each electrode shall not exceed 25%.

9. Soldering and Mounting



10. Storage and Transportation Information

Storage Conditions

To maintain the solderability of terminal electrodes:

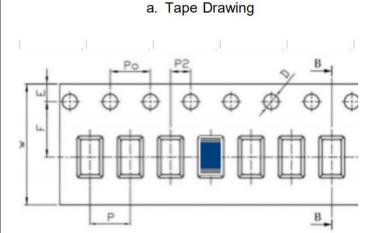
- 1. Temperature and humidity conditions: 10~ 40C and 30~70% RH.
- 2. Recommended products should be used within 6 months from the time of delivery.
- 3. The packaging material should be kept where no chlorine or sulfur exists in the air.

Transportation Conditions

- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

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- 11. Packing
- (1) Quantity/Reel: 5000 pcs/Reel
- (2) Plastic tape:



Feature	Specifications	Tolerances
W	8 00	±0 30
Р	4.00	±0.10
E	1.75	±0.10
F	3 50	±0 10
P2	2.00	±0.10
D	1.50	+0. 10
		-0.00
Po	4.00	±0.10
10Po	40 00	±0 20

b. Tape Dimensions (unit: mm)

c. Reel Drawing

